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Yamamoto

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(54) **METHOD AND APPARATUS FOR MOLDING METAL LAMINATE FILM**

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26/053; B21D 22/203; B21D 28/10;
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See application file for complete search history.

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(*) Notice: Subject to any disclaimer, the term of this
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(30) **Foreign Application Priority Data**

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(2013.01); **B21D 22/203** (2013.01); **B21D**
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(58) **Field of Classification Search**

CPC B21D 22/208; B21D 26/02; B21D 26/021;

(57) **ABSTRACT**

A punch (2) and a pad (5) are opposed to each other such that a molded portion (3a) of a metal laminate film (3) to be processed is interposed between the punch (2) and the pad (5). An enclosed space (6, 7) is compressed to raise only the temperature of the molded portion (3a) while keeping the vicinity of the molded portion (3a) at a low temperature (S1, S2). After that, the enclosed space (6, 7) is moved with respect to the molded portion (3a) to perform first molding (S3) on the molded portion (3a), and then gas in the enclosed space (6) is released to perform second molding (S4) on the

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